TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of
Invention

Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and Semiconductor-Device-and-Heat-Sink Junction

Application Number:

Date:

First Named Applicant:

Mr. Katsuhiro Itakura

Confirmation Number:

Attorney Docket Number: 39.036

I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.

I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.

Submitted By:	Elec. Sign.	Sign. Capacity
James Judge	jjUDGE	Agent
Registered Number: 42,701		

Documents being submitted:	Files
us-assignment	SM036-usassn.xml
· ·	us-assignment.xsl
	us-assignment.dtd
	assgn.tif
us-request	SM036-usrequ.xml
·	us-request.dtd
	us-request.xsl
us-fee-sheet	SM036-usfees.xml
	us-fee-sheet.xsl
	us-fee-sheet.dtd
application-body	SM036-trans.xml
.,	us-application-body.xsl
	application-body.dtd
	wipo.ent
	mathml2.dtd
	mathml2-qname-1.mod
	isoamsa.ent
	isoamsb.ent
	isoamsc.ent
	isoamsn.ent
	isoamso.ent
	isoamsr.ent
	isogrk3.ent
	isomfrk.ent
	isomopf.ent
	isomscr.ent
	isotech.ent
	isobox.ent
	isocyr1.ent
	isocyr2.ent
	isodia.ent
	isolat1.ent
	isolat2.ent
	isonum.ent
	isopub.ent
	mmlextra.ent
	mmlalias.ent
	soextblx.dtd
us-declaration	dclr01.tif
us-declaration	dclr02.tif
us-declaration	dclr03.tif
Comments	